

L Number	Hits	Search Text	DB	Time stamp
1	547	(si silicon) near2 "001"	USPAT; US-PGPUB	2004/02/12 10:14
2	52398	roughness	USPAT; US-PGPUB	2004/02/12 10:14
3	19	((si silicon) near2 "001") same roughness	USPAT; US-PGPUB	2004/02/12 12:05
4	13979	(conductive pyrolyzed pyrolyze pyrolize pyrolized) near2 carbon	USPAT; US-PGPUB	2004/02/12 14:58
5	31024	monolayer	USPAT; US-PGPUB	2004/02/12 12:07
6	342	monolayer and ((conductive pyrolyzed pyrolyze pyrolize pyrolized) near2 carbon)	USPAT; US-PGPUB	2004/02/12 12:06
7	249	monolayer and ((conductive pyrolyzed pyrolyze pyrolize pyrolized) near2 carbon)	USPAT	2004/02/12 12:06
8	23445	monolayer	USPAT; US-PGPUB	2004/02/12 12:07
9	224	monolayer and ((conductive pyrolyzed pyrolyze pyrolize pyrolized) near2 carbon)	USPAT	2004/02/12 12:07
10	31024	monolayer	USPAT; US-PGPUB	2004/02/12 12:08
11	249	monolayer and ((conductive pyrolyzed pyrolyze pyrolize pyrolized) near2 carbon)	USPAT	2004/02/12 12:19
12	941	((428/333) or (428/338)).CCLS.	USPAT; US-PGPUB	2004/02/12 14:32
13	22	((428/333) or (428/338)).CCLS.) and ((conductive pyrolyzed pyrolyze pyrolize pyrolized) near2 carbon)	USPAT; US-PGPUB	2004/02/12 14:34
14	404271	silicon	USPAT; US-PGPUB	2004/02/12 14:34
15	739	silicon same ((conductive pyrolyzed pyrolyze pyrolize pyrolized) near2 carbon)	USPAT; US-PGPUB	2004/02/12 14:34
16	605441	substrate	USPAT; US-PGPUB	2004/02/12 14:34
17	110	(silicon same ((conductive pyrolyzed pyrolyze pyrolize pyrolized) near2 carbon)) same substrate	USPAT; US-PGPUB	2004/02/12 14:34
18	11	conductive near2 (pyrolyzed pyrolyze pyrolize pyrolized) near2 carbon	USPAT; US-PGPUB	2004/02/12 14:58